

ABSTRACT

An electroplating apparatus and an electroplating system are disclosed. The electroplating apparatus (21) comprises an electroplating tank (210) configured to contain electroplating solution and a substrate (100); an insoluble anode (213) arranged inside the electroplating tank (210) and located below the substrate (100); an anode solution inlet (216) for supplying the electroplating solution into the electroplating tank; and an anode solution outlet (217) for discharging the electroplating solution from the electroplating tank. Wherein, the anode solution inlet (216) is located higher than the insoluble anode (213) and the anode solution outlet (217), so that during the electroplating, the electroplating solution flows along a first direction between the anode solution inlet and the anode solution outlet, away from the substrate. In addition, the flow rate of the electroplating solution in the electroplating tank is configured to make the electroplating solution exert a force on bubbles generated on the surface of the insoluble anode toward the first direction, and the force is greater than the buoyant force of the bubbles, thereby driving the bubbles away from the substrate and thereby overcoming the problem that the insoluble anode produces abundant bubbles during the substrate electroplating, which can affect the substrate quality.